

The products are 10MBd high-speed opto-couplers in a plastic WSOP8 package. The device consists of a high efficient AlGaAs Light Emitting Diode and a high speed optical detector. This design provides excellent AC and DC isolation between the input and output sides of the optocoupler. The output of the optical detector features an open collector Schottky clamped transistor. The ä SM H ete ° rplscal t %

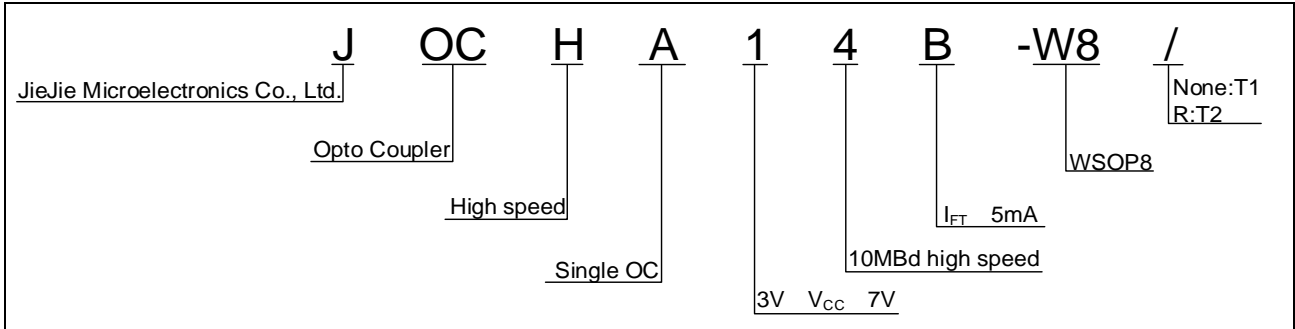
(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1	A
	Reverse Voltage	$V_R$	6	V
	Input Power Dissipation	$P_D$	100	mW

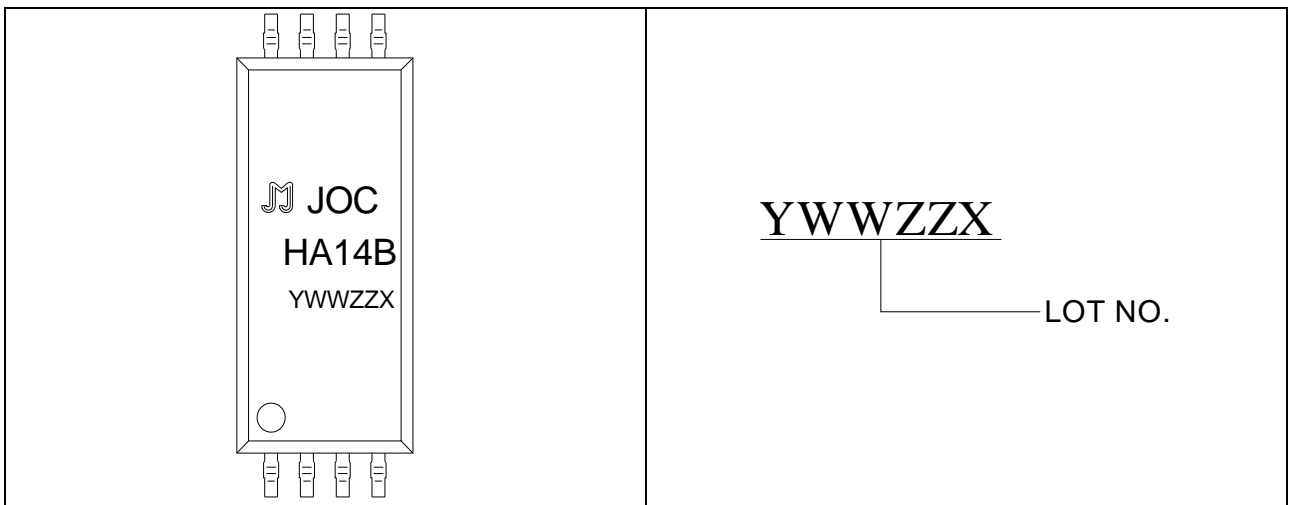
	Isolation Resistance	R <sub>ISO</sub>	DC500V 40~60%R.H.	-	10 <sup>12</sup>	-	
	Floating Capacitance	C <sub>IO</sub>	V=0, f=1MHz	-	1	-	pF
Switching Characteristics	Trigger LED Current	I <sub>FT</sub>	V <sub>CC</sub> =5V V <sub>O</sub> =V <sub>OL</sub>	-	-	5	mA
	Propagation Delay Time to Logic Low	t <sub>PHL</sub>	C <sub>L</sub> =15pF, R <sub>L</sub> =350 , I <sub>F</sub> =7.5mA	-	-	60	ns
	Propagation Delay Time to Logic High	t <sub>PLH</sub>		-	-	60	ns
	Pulse width distortion	t <sub>PHL</sub> -t <sub>PLH</sub>		-	-	35	ns
	Common Mode Transient Immunity at Logic High	CM <sub>H</sub>	V <sub>CC</sub> =3.3V, I <sub>F</sub> =0mA, V <sub>CM</sub> =1000V, R <sub>L</sub> =350	10	15	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM <sub>L</sub>	V <sub>CC</sub> =3.3V, I <sub>F</sub> =10mA, V <sub>CM</sub> =1000V, R <sub>L</sub> =350	10	15	-	kV/μs
	Rise Time	t <sub>r</sub>	C <sub>L</sub> =15pF, R <sub>L</sub> =350 , I <sub>F</sub> =7.5mA	-	30	-	ns
Fall Time	t <sub>f</sub>	-		30	-	ns	

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Operating Temperature	T <sub>a</sub>	-40	-	85	
Supply Voltage	V <sub>CC</sub>	2.7	-	3.6	V
		4.5	-	5.5	
Low Level Input Current	I <sub>FL</sub>	0	-	250	μA
High Level Input Current	I <sub>FH</sub>	7	-	15	mA

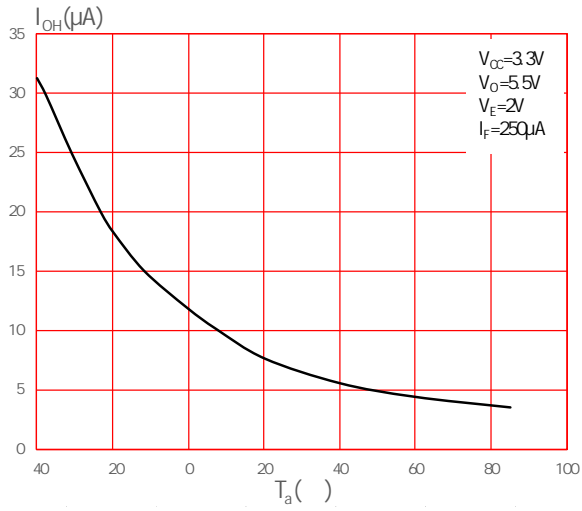
Output Pull-up Resistor	R <sub>L</sub>	330	-	4k	
Fan Out (at R <sub>L</sub> =1k per channel)	N	-	-	5	TTL Loads



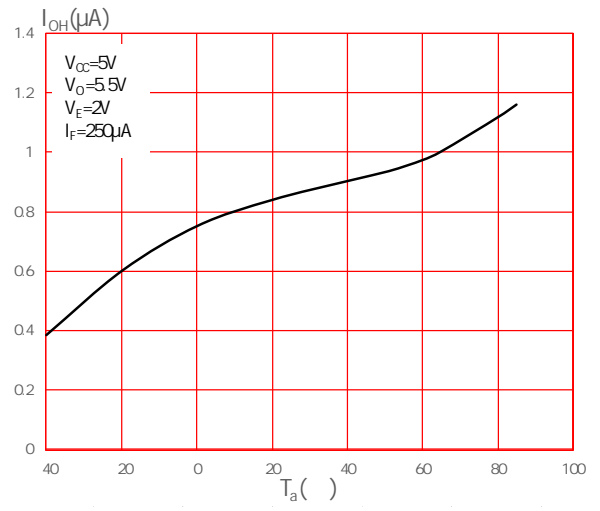
None/R	1200Units/Reel



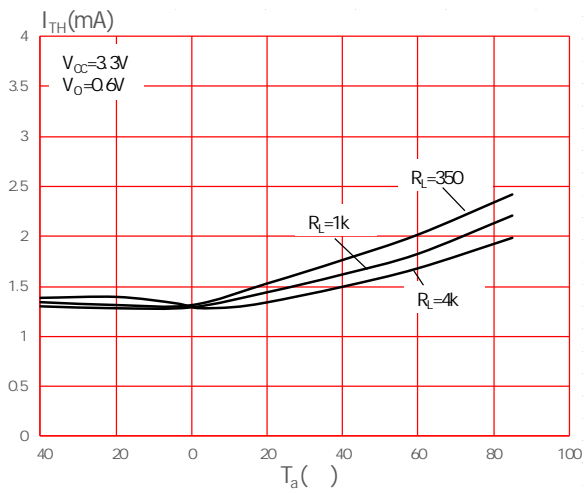
**FIG.1:** High Level Output Current vs. Ambient Temperature



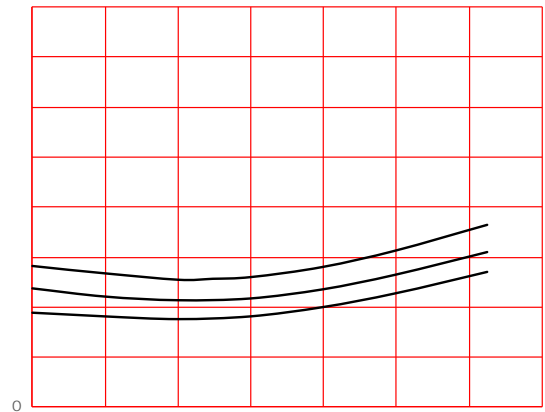
**FIG.2:** High Level Output Current vs. Ambient Temperature



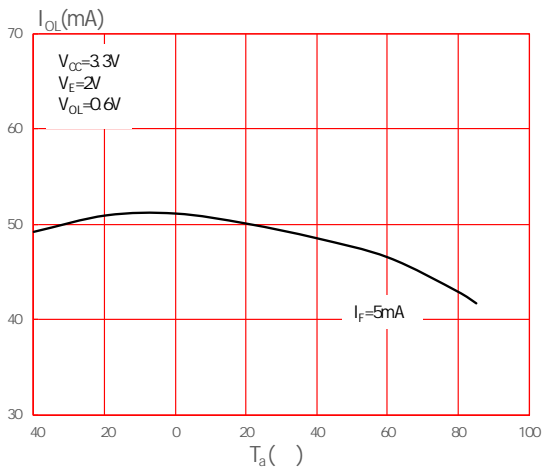
**FIG.3:** Input Threshold Current vs. Ambient Temperature



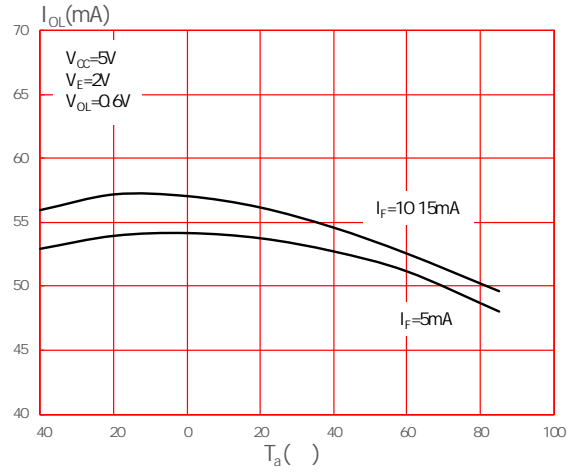
**FIG.4:** Input Threshold Current vs. Ambient Temperature



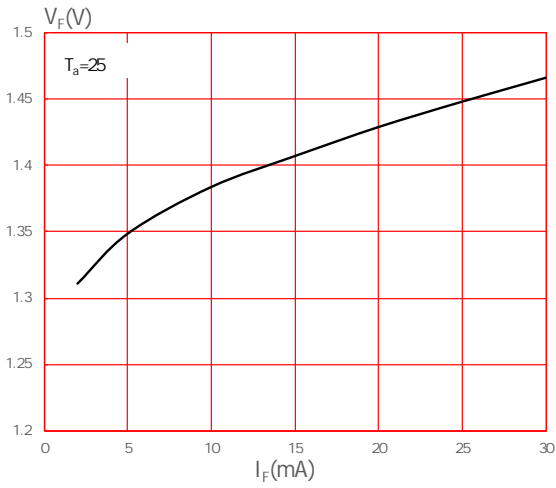
**FIG.7:** Low Level Output Current vs. Ambient Temperature



**FIG.8:** Low Level Output Current vs. Ambient Temperature



**FIG.9:** Input Forward Voltage vs. Input Forward Current



**FIG.10:** Forward Voltage vs. Ambient Temperature

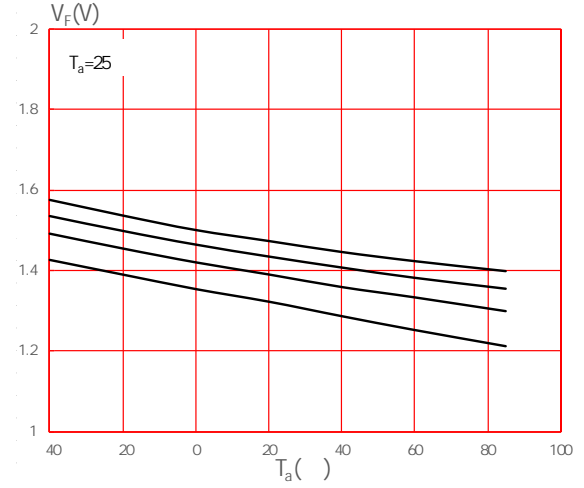


FIG.13: Pulse Width Distortion vs. Ambient Temperature

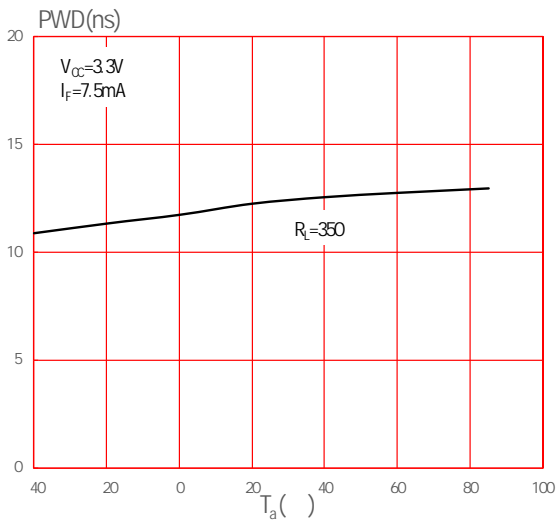


FIG.14: Pulse Width Distortion vs. Ambient Temperature

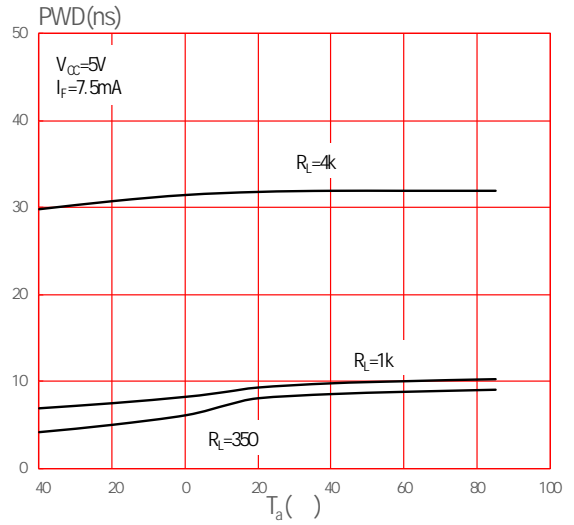
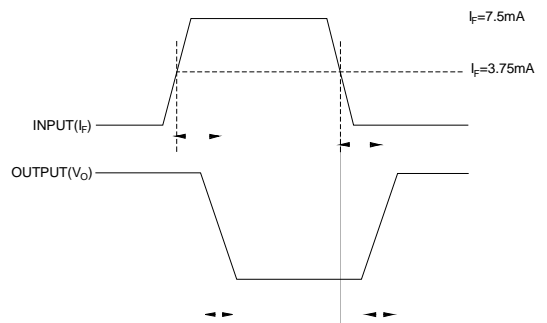
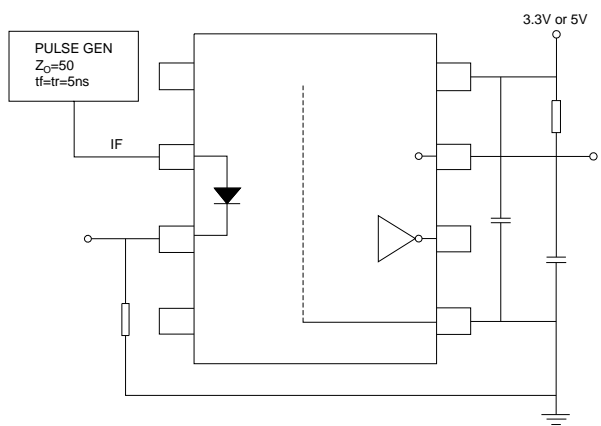
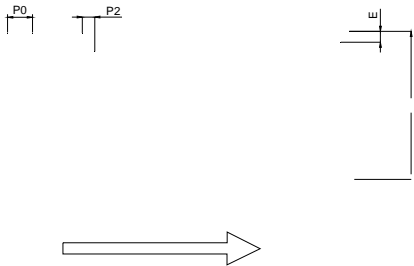


Fig.15: Test Circuit for TPHL and TPLH



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.21		0.250 66
C						
D	3.50		3.70			0.146
E	14.71		15.31			0.603
F	0.52			0.020		
G	16.36		16.86			0.664
H	0.10		0.40			0.016
I	3.65			0.144		
J			0.607	0.012		
K						






Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

 is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2026 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.